



2827

**TRANSMITTAL LETTER
(General - Patent Pending)**Docket No.
PHN16-224A

In Re Application Of: Friedl et al.

Serial No.
09/024,637Filing Date
02/17/1998Examiner
Dinh, T.Group Art Unit
2827

Title: SYNTHETIC RESIN CAPPING LAYER ON A PRINTED CIRCUIT

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is: Amendment in 4 pages

Separate Markup Sheet in 2 pages

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in the above identified application.

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Dated: October 3, 2002

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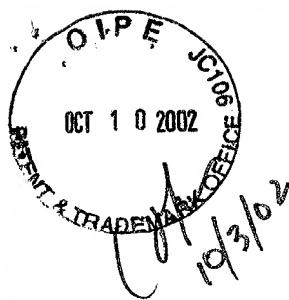
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DOCKET NO. PHN16-224A

#25/F
J. Mullinax
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Friedl et al.) Examiner: Dinh, T.
Application No.: 09/024,637) Art Unit: 2827
Filed: 02/17/1998)
For: SYNTHETIC RESIN CAPPING LAYER)
ON A PRINTED CIRCUIT)

Box Non-Fee Amendment
Commissioner for Patents
Washington D.C. 20231

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AMENDMENT

Sir:

In response to the Office Action of July 3, 2002, Applicants hereby respond as follows:

IN THE CLAIMS

Please amend claims 8 and 11 to appear as set forth below. The changes made thereto are shown in the attached Separate Markup Sheet.

8. (Four-Times Amended) A printed circuit which is provided with a synthetic resin capping layer, said circuit comprising a printed circuit board having at least one electric component, and the capping layer comprising a foam-forming reactive injection-moulding material exhibiting a variation of mechanical properties in a direction at right